ENGLISH

Datasheet

Stock No: 554-311

RS Pro Heat Sink Compound

RS 554-311 is recommended where the efficient and reliable thermal coupling of electrical and electronic components is required, or between any surface where thermal conductivity or heat dissipation is important.

It should be applied to the base and mounting studs of diodes, transistors, thyristors, heat sinks, silicone rectifiers and semi-conductors, thermostats, power resistors and radiators.

RS 554-311 is based on a silicone oil and therefore offers a wide operating temperature range and excellent stability at high temperatures.

- Very wide operating temperature range
- Excellent thermal conductivity even at high temperatures
- Low in toxicity
- White colour enables treated parts to be easily identified
- Low evaporation weight loss.

Applications include

- Semiconductor cases and heat sinks
- Power resistors and chassis, thermostats and mating surfaces, and thermoelectric cooling devices
- CPUs and GPUs
- Automatic dispensing and screen-printing
- Engine and transmission control modules
- Power supplies and UPS
- LED Power Supply
- Telecommunications and automotive electronics

Specifications:

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Approvals: RoHS-2 Compliant (2011/65/EU): Yes

Properties:

Colour:	White
Base:	Silicone oil
Thermo-conductive Component:	Powdered metal oxides
Thermal Conductivity:	0.65 W/m.K
Density @ 20°C:	2.0 g/cm3
Temperature Range:	-40°C to +200°C
Weight Loss after 96 hours @ 100°C: <1%	
Specific Resistance:	1 x 10_{14} Ohms/cm
Dielectric Strength:	16 kV/mm
Penetration:	310

Directions for Use

Apply a thin film, to the base and mounting studs of many component types including diodes, transistors, thyristors, heatsinks, silicone rectifiers, semiconductors, thermostats, power resistors and radiators.

Heat transfer compounds can be applied using a variety of methods including, screen printing, brushing and by the use of a roller.